



Material Content Data Sheet



Sales Product Name				BSC22DN20NS3 G		Issued		29. August 2013	
MA#				MA000862676					
Package				PG-TDSON-8-5		Weight*		118.72 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.916	0.77	0.77	7718	7718	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	copper	7440-50-8	37.762	31.81	31.85	318062	318476	
wire	non noble metal	copper	7440-50-8	0.066	0.06	0.06	559	559	
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		732		
	plastics	epoxy resin	-	6.173	5.20		51992		
	inorganic material	silicondioxide	60676-86-0	37.210	31.34	36.61	313414	366138	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12227	12227	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1394	1394	
solder	noble metal	silver	7440-22-4	0.030	0.02		250		
	non noble metal	tin	7440-31-5	0.024	0.02		200		
	non noble metal	lead	7439-92-1	1.135	0.96	1.00	9563	10013	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95347	95471	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	copper	7440-50-8	22.292	18.78	18.81	187760	188004	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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